

## Description

The TS5A3154 is a single-pole double-throw (SPDT) analog switch that is designed to operate from 1.65 V to 5.5 V. The device offers a low ON-state resistance and an excellent channel-to-channel ON-state resistance matching. The device has excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.

## Applications

- Cell Phones
- PDAs
- Portable Instrumentation
- Audio and Video Signal Routing
- Low-Voltage Data-Acquisition Systems
- Communication Circuits
- Modems
- Hard Drives
- Computer Peripherals
- Wireless Terminals and Peripherals

## Features

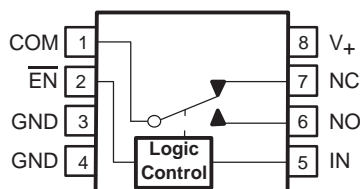
- Specified Make-Before-Break Switching
- Low ON-State Resistance (0.9 Ω)
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

## Summary of Characteristics

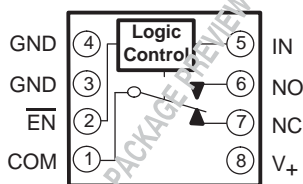
$V_+ = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

Configuration	Single Pole, Double Throw 2:1 Multiplexer/ Demultiplexer (SPDT)
Number of channels	1
ON-state resistance ( $r_{ON}$ )	0.9 Ω
ON-state resistance match ( $\Delta r_{ON}$ )	0.1 Ω
ON-state resistance flatness ( $r_{ON(flat)}$ )	0.15 Ω
Turn-on/turn-off time ( $t_{ON}/t_{OFF}$ )	8 ns/12.5 ns
Make-before-break time ( $t_{MBB}$ )	12 ns
Charge injection ( $Q_C$ )	10 pC
Bandwidth (BW)	100 MHz
OFF isolation ( $O_{ISO}$ )	–64 dB at 1 MHz
Crosstalk ( $X_{TALK}$ )	–64 dB at 1 MHz
Total harmonic distortion (THD)	0.004%
Leakage current ( $I_{COM(OFF)}/I_{NC(OFF)}$ )	±20 nA
Power-supply current ( $I_+$ )	0.1 μA
Package option	8-pin SSOP, SOT, or DSBGA

SSOP OR SOT PACKAGE  
(TOP VIEW)



YEA, YEP, YZA, OR YZP PACKAGE  
(BOTTOM VIEW)



FUNCTION TABLE

$\overline{EN}$	IN	NC TO COM, COM TO NC	NO TO COM, COM TO NO
L	L	ON	OFF
L	H	OFF	ON
H	X	OFF	OFF



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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**TS5A3154**  
**0.9-Ω SPDT ANALOG SWITCH**  
**5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER**

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**ORDERING INFORMATION**

<b>T<sub>A</sub></b>	<b>PACKAGE(1)</b>		<b>ORDERABLE PART NUMBER</b>	<b>TOP-SIDE MARKING(2)</b>
–40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA	Tape and reel	TS5A3154YEAR	
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)		TS5A3154YZAR	
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		TS5A3154YEPR	
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		TS5A3154YZPR	
	SSOP – DCT (Pb-free)	Tape	TS5A3154DCTRE6	JCF____
	DCU (Pb-free)	Tape and reel	TS5A3154DCURE6	JCF____, ____

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

(2) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, ● = Pb-free).

## Absolute Minimum and Maximum Ratings<sup>(1)(2)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_+$	Supply voltage range <sup>(3)</sup>		-0.5	6.5	V
$V_{NC}$ $V_{NO}$ $V_{COM}$	Analog voltage range <sup>(3)(4)(5)</sup>		-0.5	$V_+ + 0.5$	V
$I_K$	Analog port diode current	$V_{NC}, V_{NO}, V_{COM} < 0$ or $V_{NC}, V_{NO}, V_{COM} > V_+$	-50	50	mA
$I_{NC}$ $I_{NO}$ $I_{COM}$	On-state switch current	$V_{NC}, V_{NO}, V_{COM} = 0$ to $V_+$	-200	200	mA
	On-state peak switch current <sup>(6)</sup>		-400	400	
$V_I$	Digital input voltage range <sup>(3)(4)</sup>		-0.5	6.5	V
$I_{IK}$	Digital input clamp current	$V_I < 0$	-50		mA
$I_+$	Continuous current through $V_+$			100	mA
$I_{GND}$	Continuous current through GND		-100	100	mA
$\theta_{JA}$	Package thermal impedance <sup>(7)</sup>	DCT package		220	°C/W
		DCU package		227	
		YEA/YZA package		140	
		YEP/YZP package		102	
$T_{stg}$	Storage temperature range		-65	150	°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(3) All voltages are with respect to ground, unless otherwise specified.

(4) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(5) This value is limited to 5.5 V maximum.

(6) Pulse at 1-ms duration < 10% duty cycle.

(7) The package thermal impedance is calculated in accordance with JESD 51-7.

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**5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER**

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**Electrical Characteristics for 5-V Supply<sup>(1)</sup>**

$V_+ = 4.5\text{ V to }5.5\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V <sub>COM</sub> , V <sub>NO</sub> , V <sub>NC</sub>					0		V <sub>+</sub>	V
Peak ON resistance	r <sub>peak</sub>	0 ≤ (V <sub>NO</sub> or V <sub>NC</sub> ) ≤ V <sub>+</sub> , I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25 °C Full	4.5 V	0.9	1.1		Ω
ON-state resistance	r <sub>on</sub>	V <sub>NO</sub> or V <sub>NC</sub> = 2.5 V, I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25°C Full	4.5 V	0.8	0.9		Ω
ON-state resistance match between channels	Δr <sub>on</sub>	V <sub>NO</sub> or V <sub>NC</sub> = 2.5 V, I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25°C Full	4.5 V	0.05	0.1		Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	0 ≤ (V <sub>NO</sub> or V <sub>NC</sub> ) ≤ V <sub>+</sub> , I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25°C	4.5 V	0.15		Ω	
				Full					
		V <sub>NO</sub> or V <sub>NC</sub> = 1 V, 1.5 V, 2.5 V, I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25°C		0.09 0.15			
				Full		0.15			
NC, NO OFF leakage current	I <sub>NC(OFF)</sub> , I <sub>NO(OFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 1 V, V <sub>COM</sub> = 4.5 V, or V <sub>NC</sub> or V <sub>NO</sub> = 4.5 V, V <sub>COM</sub> = 1 V,	Switch OFF, See Figure 14	25°C	5.5 V	−20	2	20	nA
				Full		−150		150	
	I <sub>NC(PWROFF)</sub> , I <sub>NO(PWROFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 0 to 5.5 V, V <sub>COM</sub> = 5.5 V to 0,	Switch OFF, See Figure 14	25°C	0 V	−5	0.7	5	μA
				Full		−25		25	
NC, NO ON leakage current	I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 1 V, V <sub>COM</sub> = Open, or V <sub>NC</sub> or V <sub>NO</sub> = 4.5 V, V <sub>COM</sub> = Open,	Switch ON, See Figure 15	25°C	5.5 V	−20	2	20	nA
				Full		−150		150	
COM OFF leakage current	I <sub>COM(OFF)</sub>	V <sub>COM</sub> = 1 V, V <sub>NC</sub> or V <sub>NO</sub> = 4.5 V, or V <sub>COM</sub> = 4.5 V, V <sub>NC</sub> or V <sub>NO</sub> = 1 V,	Switch OFF See Figure 14	25°C	5.5 V	−20	2	20	nA
				Full		−150		150	
	I <sub>COM(PWROFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 0 to 5.5 V, V <sub>COM</sub> = 5.5 V to 0,	Switch OFF, See Figure 14	25°C	0 V	−5	0.7	5	μA
				Full		−25		25	
COM ON leakage current	I <sub>COM(ON)</sub>	V <sub>COM</sub> = 1 V, V <sub>NC</sub> or V <sub>NO</sub> = Open, or V <sub>COM</sub> = 4.5 V, V <sub>NC</sub> or V <sub>NO</sub> = Open	Switch ON, See Figure 15	25°C	5.5 V	−20	2	20	nA
				Full		−150		150	
Digital Control Inputs (I <sub>N</sub> , $\overline{\text{EN}}$ )(2)									
Input logic high	V <sub>IH</sub>			Full		2.4		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		0.8	V
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C	5.5 V	−100	25	100	nA
				Full		−100		100	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at  $V_+$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## Electrical Characteristics for 5-V Supply<sup>(1)</sup> (continued)

$V_+ = 4.5 \text{ V to } 5.5 \text{ V}$ ,  $T_A = -40^\circ\text{C to } 85^\circ\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time, IN or $\overline{\text{OE}}$	t <sub>ON</sub>	V <sub>COM</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 17	25°C	5 V	1	5.2	8	ns
				Full	4.5 V to 5.5 V	1		9	
Turn-off time, IN or $\overline{\text{OE}}$	t <sub>OFF</sub>	V <sub>COM</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 17	25°C	5 V	5	9.5	12.5	ns
				Full	4.5 V to 5.5 V	4		13.5	
Make-before-break time	t <sub>MBB</sub>	V <sub>COM</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 18	25°C	5 V	4	6.3	12	ns
				Full	4.5 V to 5.5 V	4		13	
Charge injection	Q <sub>C</sub>	V <sub>GEN</sub> = 0, R <sub>GEN</sub> = 0,	C <sub>L</sub> = 1 nF, See Figure 22	25°C	5 V		10		pC
NC, NO OFF capacitance	C <sub>NC(OFF)</sub> , C <sub>NO(OFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 16	25°C	5 V		19		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	5 V		57		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	5 V		36		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	5 V		57		pF
Digital input capacitance	C <sub>I</sub>	V <sub>I</sub> = V <sub>+</sub> or GND,	See Figure 16	25°C	5 V		2		pF
Bandwidth	BW	R <sub>L</sub> = 50 Ω, Switch ON,	See Figure 19	25°C	5 V		100		MHz
OFF isolation	O <sub>ISO</sub>	R <sub>L</sub> = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 20	25°C	5 V		−64		dB
Crosstalk	X <sub>TALK</sub>	R <sub>L</sub> = 50 Ω, f = 1 MHz,	Switch ON, See Figure 21	25°C	5 V		−64		dB
Total harmonic distortion	THD	R <sub>L</sub> = 600 Ω, C <sub>L</sub> = 50 pF,	f = 20 Hz to 20 kHz, See Figure 23	25°C	5 V		0.004		%
Supply									
Positive supply current	I <sub>+</sub>	V <sub>I</sub> = V <sub>+</sub> or GND,	Switch ON or OFF	25°C	5.5 V	0.02		0.1	μA
				Full				0.5	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

**TS5A3154**  
**0.9-Ω SPDT ANALOG SWITCH**  
**5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER**

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**Electrical Characteristics for 3.3-V Supply<sup>(1)</sup>**

$V_+ = 3\text{ V to }3.6\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V <sub>COM</sub> , V <sub>NO</sub> , V <sub>NC</sub>					0		V <sub>+</sub>	V
Peak ON resistance	r <sub>peak</sub>	0 ≤ (V <sub>NO</sub> or V <sub>NC</sub> ) ≤ V <sub>+</sub> , I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25 °C Full	3 V	1.3    1.6		Ω	
ON-state resistance	r <sub>on</sub>	V <sub>NO</sub> or V <sub>NC</sub> = 2 V, I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25°C Full	3 V	1.2    1.5			
ON-state resistance match between channels	Δr <sub>on</sub>	V <sub>NO</sub> or V <sub>NC</sub> = 2 V, 0.8 V, I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25°C Full	3 V	0.08    0.15		Ω	
ON-state resistance flatness	r <sub>on(flat)</sub>	0 ≤ (V <sub>NO</sub> or V <sub>NC</sub> ) ≤ V <sub>+</sub> , I <sub>COM</sub> = −100 mA,	Switch ON, See Figure 13	25°C Full	3 V	0.3			Ω
				V <sub>NO</sub> or V <sub>NC</sub> = 2 V, 0.8 V, I <sub>COM</sub> = −100 mA,		Switch ON, See Figure 13	25°C Full	0.09    0.15	
NC, NO OFF leakage current	I <sub>NO(OFF)</sub> , I <sub>NC(OFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 1 V, V <sub>COM</sub> = 3 V, or V <sub>NC</sub> or V <sub>NO</sub> = 3 V, V <sub>COM</sub> = 1 V,	Switch OFF, See Figure 14	25°C Full	3.6 V	−20	2	20	nA
	I <sub>NO(PWROFF)</sub> , I <sub>NC(PWROFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 0 to 3.6 V, V <sub>COM</sub> = 3.6 V to 0,	Switch OFF, See Figure 14	25°C Full	0 V	−1	0.2	1	μA
NC, NO ON leakage current	I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 1 V, V <sub>COM</sub> = Open, or V <sub>NC</sub> or V <sub>NO</sub> = 3 V, V <sub>COM</sub> = Open,	Switch ON, See Figure 15	25°C Full	3.6 V	−20	2	20	nA
COM OFF leakage current	I <sub>COM(OFF)</sub>	V <sub>COM</sub> = 1 V, V <sub>NC</sub> or V <sub>NO</sub> = 3 V, or V <sub>COM</sub> = 3 V, V <sub>NC</sub> or V <sub>NO</sub> = 1 V,	Switch OFF, See Figure 14	25°C Full	3.6 V	−20	2	20	nA
	I <sub>COM(PWROFF)</sub>	V <sub>COM</sub> = 0 to 3.6 V, V <sub>NC</sub> or V <sub>NO</sub> = 3.6 V to 0,	Switch OFF, See Figure 14	25°C Full	0 V	−1	0.2	1	μA
COM ON leakage current	I <sub>COM(ON)</sub>	V <sub>COM</sub> = 1 V, V <sub>NC</sub> or V <sub>NO</sub> = Open, or V <sub>COM</sub> = 3 V, V <sub>NC</sub> or V <sub>NO</sub> = Open	Switch ON, See Figure 15	25°C Full	3.6 V	−20	2	20	nA
Digital Control Inputs (I <sub>N</sub> , $\overline{\text{EN}}$ )(2)									
Input logic high	V <sub>IH</sub>			Full		2		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		0.8	V
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C	3.6 V	−100	25	100	nA
				Full		−100		100	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at  $V_+$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## Electrical Characteristics for 3.3-V Supply<sup>(1)</sup> (continued)

$V_+ = 3\text{ V to }3.6\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	$T_A$	$V_+$	MIN	TYP	MAX	UNIT
<b>Dynamic</b>								
Turn-on time	$t_{ON}$	$V_{COM} = V_+$ , $R_L = 50\ \Omega$ , $C_L = 35\text{ pF}$ , See Figure 17	25°C	3.3 V	3	6	10	ns
			Full	3 V to 3.6 V	2		10.5	
Turn-off time	$t_{OFF}$	$V_{COM} = V_+$ , $R_L = 50\ \Omega$ , $C_L = 35\text{ pF}$ , See Figure 17	25°C	3.3 V	5	10	15	ns
			Full	3 V to 3.6 V	4		17	
Make-before-break time	$t_{MBB}$	$V_{COM} = V_+$ , $R_L = 50\ \Omega$ , $C_L = 35\text{ pF}$ , See Figure 18	25°C	3.3 V	4	5.7	12	ns
			Full	3 V to 3.6 V	4		13	
Charge injection	$Q_C$	$V_{GEN} = 0$ , $R_{GEN} = 0$ , $C_L = 1\text{ nF}$ , See Figure 22	25°C	3.3 V		9		pC
NC, NO OFF capacitance	$C_{NC(OFF)}$ , $C_{NO(OFF)}$	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch OFF, See Figure 16	25°C	3.3 V		19		pF
NC, NO ON capacitance	$C_{NC(ON)}$ , $C_{NO(ON)}$	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch ON, See Figure 16	25°C	3.3 V		57		pF
COM OFF capacitance	$C_{COM(OFF)}$	$V_{COM} = V_+$ or GND, Switch ON, See Figure 16	25°C	3.3 V		36		pF
COM ON capacitance	$C_{COM(ON)}$	$V_{COM} = V_+$ or GND, Switch ON, See Figure 16	25°C	3.3 V		57		pF
Digital input capacitance	$C_I$	$V_I = V_+$ or GND, See Figure 16	25°C	3.3 V		2		pF
Bandwidth	BW	$R_L = 50\ \Omega$ , Switch ON, See Figure 19	25°C	3.3 V		100		MHz
OFF isolation	$O_{ISO}$	$R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ , Switch OFF, See Figure 20	25°C	3.3 V		-64		dB
Crosstalk	$X_{TALK}$	$R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ , Switch ON, See Figure 21	25°C	3.3 V		-64		dB
Total harmonic distortion	THD	$R_L = 600\ \Omega$ , $C_L = 50\text{ pF}$ , $f = 20\text{ Hz to }20\text{ kHz}$ , See Figure 23	25°C	3.3 V		0.010		%
<b>Supply</b>								
Positive supply current	$I_+$	$V_I = V_+$ or GND, Switch ON or OFF	25°C	3.6 V		0.01	0.1	$\mu\text{A}$
			Full				0.25	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

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**Electrical Characteristics for 2.5-V Supply<sup>(1)</sup>**

$V_+ = 2.3 \text{ V to } 2.7 \text{ V}$ ,  $T_A = -40^\circ\text{C to } 85^\circ\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V <sub>COM</sub> , V <sub>NO</sub> , V <sub>NC</sub>					0		V <sub>+</sub>	V
Peak ON resistance	r <sub>peak</sub>	0 ≤ (V <sub>NO</sub> or V <sub>NC</sub> ) ≤ V <sub>+</sub> , I <sub>COM</sub> = −8 mA,	Switch ON, See Figure 13	25 °C Full	2.3 V	1.9		2.5	Ω
ON-state resistance	r <sub>on</sub>	V <sub>NO</sub> or V <sub>NC</sub> = 1.8 V, I <sub>COM</sub> = −8 mA,	Switch ON, See Figure 13	25°C Full	2.3 V	1.6		2.1	Ω
ON-state resistance match between channels	Δr <sub>on</sub>	V <sub>NO</sub> or V <sub>NC</sub> = 1.8 V, I <sub>COM</sub> = −8 mA,	Switch ON, See Figure 13	25°C Full	2.3 V	0.12		0.2	Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	0 ≤ (V <sub>NO</sub> or V <sub>NC</sub> ) ≤ V <sub>+</sub> , I <sub>COM</sub> = −8 mA,	Switch ON, See Figure 13	25°C	2.3 V	0.65		Ω	
				Full					
		V <sub>NO</sub> or V <sub>NC</sub> = 0.8 V, 1.8 V, I <sub>COM</sub> = −8 mA,	Switch ON, See Figure 13	25°C		0.5			1
				Full		1			
NC, NO OFF leakage current	I <sub>NO(OFF)</sub> , I <sub>NC(OFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 0.5 V, V <sub>COM</sub> = 2.3 V, or V <sub>NC</sub> or V <sub>NO</sub> = 2.3 V, V <sub>COM</sub> = 0.5 V,	Switch OFF, See Figure 14	25°C	2.7 V	−20	2	20	nA
				Full		−50	50		
	I <sub>NO(PWROFF)</sub> , I <sub>NC(PWROFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 0 to 2.7 V, V <sub>COM</sub> = 2.7 V to 0,	Switch OFF, See Figure 14	25°C	0 V	−1	0.1	1	μA
				Full		−10	10		
NC, NO ON leakage current	I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = 0.5 V, V <sub>COM</sub> = Open, or V <sub>NC</sub> or V <sub>NO</sub> = 2.3 V, V <sub>COM</sub> = Open,	Switch ON, See Figure 15	25°C	2.7 V	−20	2	20	nA
				Full		−50	50		
COM OFF leakage current	I <sub>COM(OFF)</sub>	V <sub>COM</sub> = 0.5 V, V <sub>NC</sub> or V <sub>NO</sub> = 2.3 V, or V <sub>COM</sub> = 2.3 V, V <sub>NC</sub> or V <sub>NO</sub> = 0.5 V,	Switch OFF, See Figure 14	25°C	2.7 V	−20	2	20	nA
				Full		−50	50		
	I <sub>COM(PWROFF)</sub>	V <sub>COM</sub> = 0 to 2.7 V, V <sub>NC</sub> or V <sub>NO</sub> = 2.7 V to 0,	Switch OFF, See Figure 14	25°C	0 V	−1	0.1	1	μA
				Full		−10	10		
COM ON leakage current	I <sub>COM(ON)</sub>	V <sub>COM</sub> = 0.5 V, V <sub>NC</sub> or V <sub>NO</sub> = Open, or V <sub>COM</sub> = 2.3 V, V <sub>NC</sub> or V <sub>NO</sub> = Open,	Switch ON, See Figure 15	25°C	2.7 V	−20	2	20	nA
				Full		−50	50		
Digital Control Inputs (I <sub>N</sub> , $\overline{\text{EN}}$ )(2)									
Input logic high	V <sub>IH</sub>			Full		1.8		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		0.6	V
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C	2.7 V	−100	25	100	nA
				Full		−100	100		

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at  $V_+$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



## Electrical Characteristics for 2.5-V Supply<sup>(1)</sup> (continued)

$V_+ = 2.3 \text{ V to } 2.7 \text{ V}$ ,  $T_A = -40^\circ\text{C to } 85^\circ\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	t <sub>ON</sub>	V <sub>COM</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 17	25°C	2.5 V	4	7.0	11.5	ns
				Full	2.3 V to 2.7 V	3.5		12	
Turn-off time	t <sub>OFF</sub>	V <sub>COM</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 17	25°C	2.5 V	5	11.5	18.5	ns
				Full	2.3 V to 2.7 V	4		21	
Make-before-break time	t <sub>MBB</sub>	V <sub>COM</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 18	25°C	2.5 V	4	6.3	15	ns
				Full	2.3 V to 2.7 V	4		16	
Charge injection	Q <sub>C</sub>	V <sub>GEN</sub> = 0, R <sub>GEN</sub> = 0,	C <sub>L</sub> = 1 nF, See Figure 22	25°C	2.5 V		7		pC
NC, NO OFF capacitance	C <sub>NC(OFF)</sub> , C <sub>NO(OFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 16	25°C	2.5 V		19		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	2.5 V		57		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	2.5 V		36		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	2.5 V		57		pF
Digital input capacitance	C <sub>I</sub>	V <sub>I</sub> = V <sub>+</sub> or GND,	See Figure 16	25°C	2.5 V		2		pF
Bandwidth	BW	R <sub>L</sub> = 50 Ω, Switch ON,	See Figure 19	25°C	2.5 V		100		MHz
OFF isolation	O <sub>ISO</sub>	R <sub>L</sub> = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 20	25°C	2.5 V		−64		dB
Crosstalk	X <sub>TALK</sub>	R <sub>L</sub> = 50 Ω, f = 1 MHz,	Switch ON, See Figure 21	25°C	2.5 V		−64		dB
Total harmonic distortion	THD	R <sub>L</sub> = 600 Ω, C <sub>L</sub> = 50 pF,	f = 20 Hz to 20 kHz, See Figure 23	25°C	2.5 V		0.020		%
Supply									
Positive supply current	I <sub>+</sub>	V <sub>I</sub> = V <sub>+</sub> or GND,	Switch ON or OFF	25°C	2.7 V	0.001	0.05		μA
				Full			0.15		

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

**TS5A3154**  
**0.9-Ω SPDT ANALOG SWITCH**  
**5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER**

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**Electrical Characteristics for 1.8-V Supply<sup>(1)</sup>**

$V_+ = 1.65\text{ V to }1.95\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	$T_A$	$V_+$	MIN	TYP	MAX	UNIT
<b>Analog Switch</b>								
Analog signal range	$V_{COM}, V_{NO}, V_{NC}$				0		$V_+$	V
Peak ON resistance	$r_{peak}$	$0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_+$ , $I_{COM} = -2\text{ mA}$ , Switch ON, See Figure 13	25°C Full	1.65 V		5.5	25 30	Ω
ON-state resistance	$r_{on}$	$V_{NO} \text{ or } V_{NC} = 1.5\text{ V}$ , $I_{COM} = -2\text{ mA}$ , Switch ON, See Figure 13	25°C Full	1.65 V		2.0	2.7 3.1	Ω
ON-state resistance match between channels	$\Delta r_{on}$	$V_{NO} \text{ or } V_{NC} = 0.6\text{ V}, 1.5\text{ V}$ , $I_{COM} = -2\text{ mA}$ , Switch ON, See Figure 13	25°C Full	1.65 V		0.16	0.3 0.3	Ω
ON-state resistance flatness	$r_{on(flat)}$	$0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_+$ , $I_{COM} = -2\text{ mA}$ , Switch ON, See Figure 13	25°C Full	1.65 V		3	20 25	Ω
NC, NO OFF leakage current	$I_{NO(OFF)}, I_{NC(OFF)}$	$V_{NC} \text{ or } V_{NO} = 0.3\text{ V}, V_{COM} = 1.65\text{ V}$ , or $V_{NC} \text{ or } V_{NO} = 1.65\text{ V}, V_{COM} = 0.3\text{ V}$ , Switch OFF, See Figure 14	25°C Full	1.95 V	-20	1.5	20 50	nA
	$I_{NOPWROFF}, I_{NCPWROFF}$	$V_{NC} \text{ or } V_{NO} = 0 \text{ to } 1.95\text{ V}$ , $V_{COM} = 1.95\text{ V to } 0$ , Switch OFF, See Figure 14	25°C Full	0 V	-1	0.1	1 10	μA
NC, NO ON leakage current	$I_{NC(ON)}, I_{NO(ON)}$	$V_{NC} \text{ or } V_{NO} = 0.3\text{ V}, V_{COM} = \text{Open}$ , or $V_{NC} \text{ or } V_{NO} = 1.65\text{ V}, V_{COM} = \text{Open}$ , Switch ON, See Figure 15	25°C Full	1.95 V	-20	1.5	20 50	nA
	$I_{COM(OFF)}$	$V_{NC} \text{ or } V_{NO} = 1.65\text{ V}, V_{COM} = 0.3\text{ V}$ , or $V_{NC} \text{ or } V_{NO} = 0.3\text{ V}, V_{COM} = 1.65\text{ V}$ , Switch OFF, See Figure 14	25°C Full	1.95 V	-20	1.5	20 50	nA
COM OFF leakage current	$I_{COM(PWROFF)}$	$V_{NC} \text{ or } V_{NO} = 1.95\text{ V to } 0$ , $V_{COM} = 0 \text{ to } 1.95\text{ V}$ , Switch OFF, See Figure 14	25°C Full	0 V	-1	0.06	1 10	μA
	$I_{COM(ON)}$	$V_{NC} \text{ or } V_{NO} = \text{Open}, V_{COM} = 0.3\text{ V}$ , or $V_{NC} \text{ or } V_{NO} = \text{Open}, V_{COM} = 1.65\text{ V}$ , Switch ON, See Figure 15	25°C Full	1.95 V	-20	1.5	20 50	nA
<b>Digital Control Inputs (<math>\overline{IN}</math>, <math>\overline{EN}</math>)<sup>(2)</sup></b>								
Input logic high	$V_{IH}$		Full		1.5		5.5	V
Input logic low	$V_{IL}$		Full		0		0.6	V
Input leakage current	$I_{IH}, I_{IL}$	$V_I = 5.5\text{ V or } 0$	25°C Full	1.95 V	-100	25	100 100	nA

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at  $V_+$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## Electrical Characteristics for 1.8-V Supply<sup>(1)</sup> (continued)

$V_+ = 1.65 \text{ V to } 1.95 \text{ V}$ ,  $T_A = -40^\circ\text{C to } 85^\circ\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	t <sub>ON</sub>	V <sub>COM</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 17	25°C	1.8 V	5	10.5	20.5	ns
				Full	1.65 V to 1.95 V	4.5		21	
Turn-off time	t <sub>OFF</sub>	V <sub>COM</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 17	25°C	1.8 V	7	16.5	27.5	ns
				Full	1.65 V to 1.95 V	5		30	
Break-before-make time	t <sub>BBM</sub>	V <sub>NC</sub> = V <sub>NO</sub> = V <sub>+</sub> , R <sub>L</sub> = 50 Ω,	C <sub>L</sub> = 35 pF, See Figure 18	25°C	1.8 V	4	8.3	15	ns
				Full	1.65 V to 1.95 V	4		16	
Charge injection	Q <sub>C</sub>	V <sub>GEN</sub> = 0, R <sub>GEN</sub> = 0,	C <sub>L</sub> = 1 nF, See Figure 22	25°C	1.8 V		5		pC
NC, NO OFF capacitance	C <sub>NC(OFF)</sub> , C <sub>NO(OFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 16	25°C	1.8 V		19		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	1.8 V		57		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 16	25°C	1.8 V		36		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	1.8 V		57		pF
Digital input capacitance	C <sub>I</sub>	V <sub>I</sub> = V <sub>+</sub> or GND,	See Figure 16	25°C	1.8 V		2.0		pF
Bandwidth	BW	R <sub>L</sub> = 50 Ω, Switch ON,	See Figure 19	25°C	1.8 V		100		MHz
OFF isolation	O <sub>ISO</sub>	R <sub>L</sub> = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 20	25°C	1.8 V		−64		dB
Crosstalk	X <sub>TALK</sub>	R <sub>L</sub> = 50 Ω, f = 1 MHz,	Switch ON, See Figure 21	25°C	1.8 V		−64		dB
Total harmonic distortion	THD	R <sub>L</sub> = 600 Ω, C <sub>L</sub> = 50 pF,	f = 20 Hz to 20 kHz, See Figure 23	25°C	1.8 V		0.060		%
Supply									
Positive supply current	I <sub>+</sub>	V <sub>I</sub> = V <sub>+</sub> or GND,	Switch ON or OFF	25°C	1.95 V		0.001	0.05	μA
				Full				0.1	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

## TYPICAL PERFORMANCE

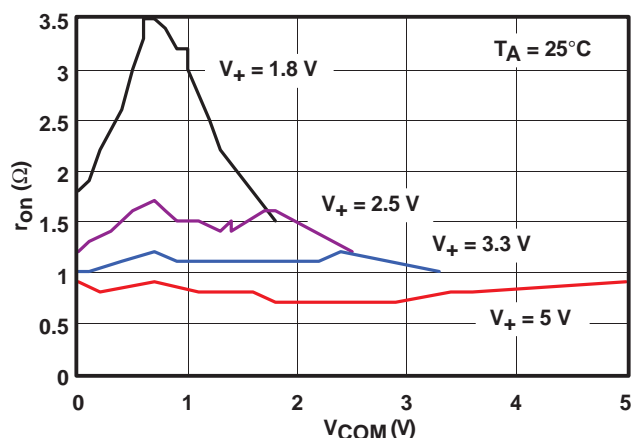


Figure 1.  $r_{on}$  vs  $V_{COM}$

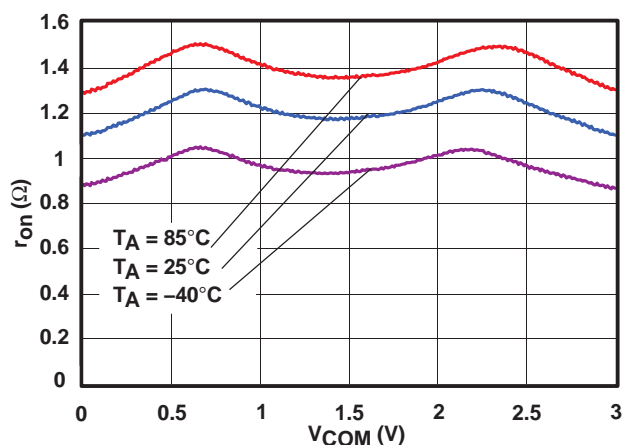


Figure 2.  $r_{on}$  vs  $V_{COM}$  ( $V_+ = 3$  V)

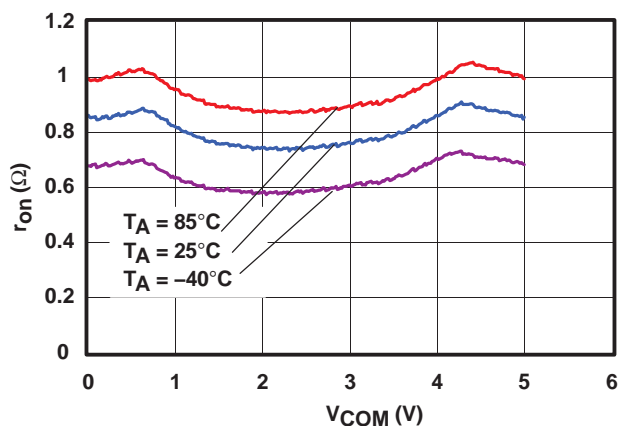


Figure 3.  $r_{on}$  vs  $V_{COM}$  ( $V_+ = 5$  V)

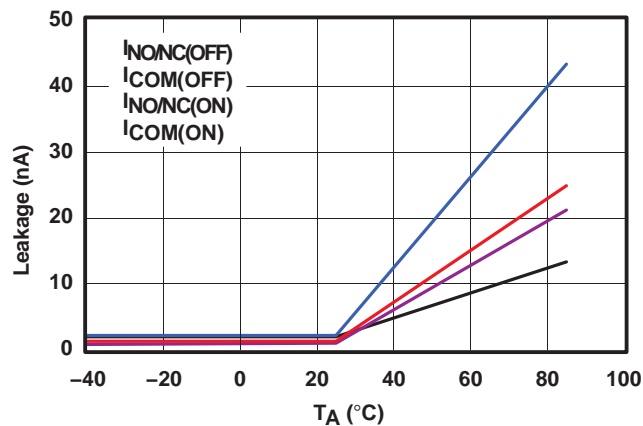


Figure 4. Leakage Current vs Temperature  
( $V_+ = 5.5$  V)

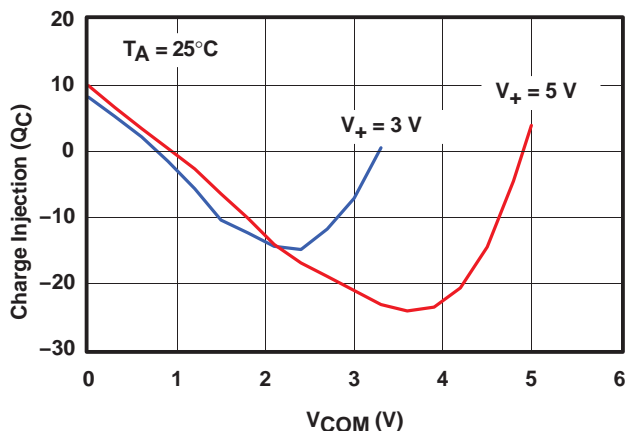


Figure 5. Charge Injection ( $Q_C$ ) vs  $V_{COM}$

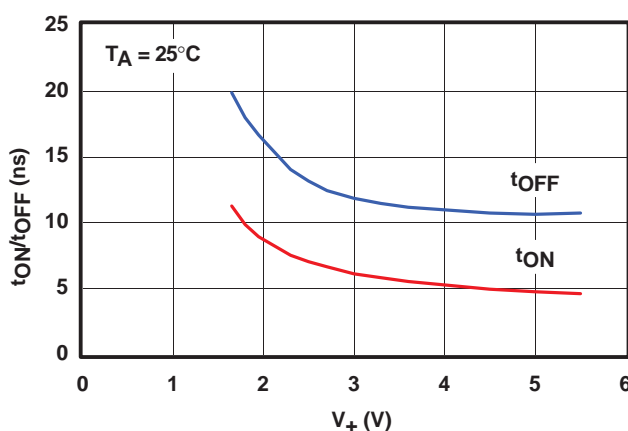


Figure 6.  $t_{ON}$  and  $t_{OFF}$  vs Supply Voltage

# TYPICAL PERFORMANCE

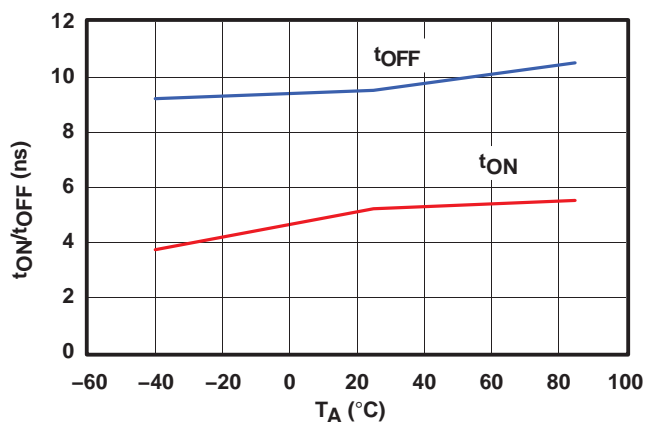


Figure 7.  $t_{ON}$  and  $t_{OFF}$  vs Temperature ( $V_+ = 5$  V)

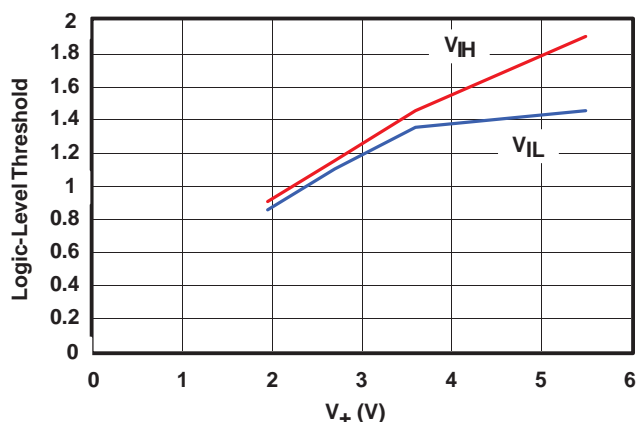


Figure 8. Logic-Level Threshold vs  $V_+$

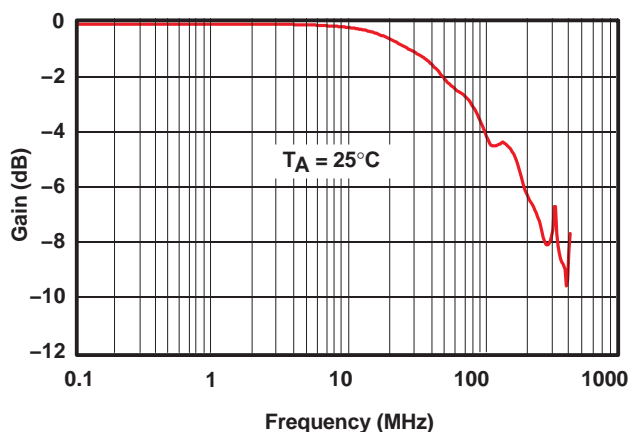


Figure 9. Bandwidth ( $V_+ = 5$  V)

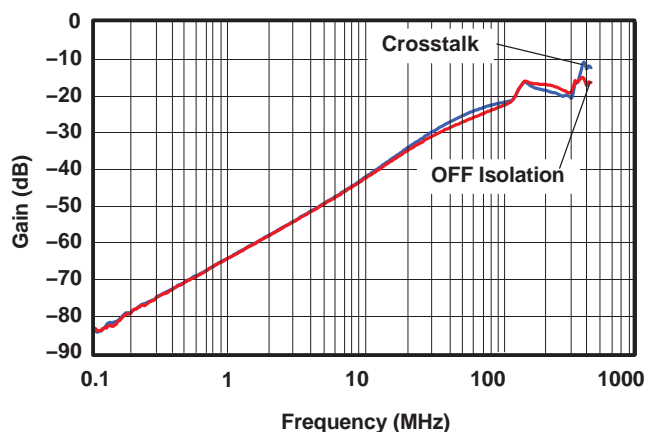


Figure 10. OFF Isolation and Crosstalk ( $V_+ = 5$  V)

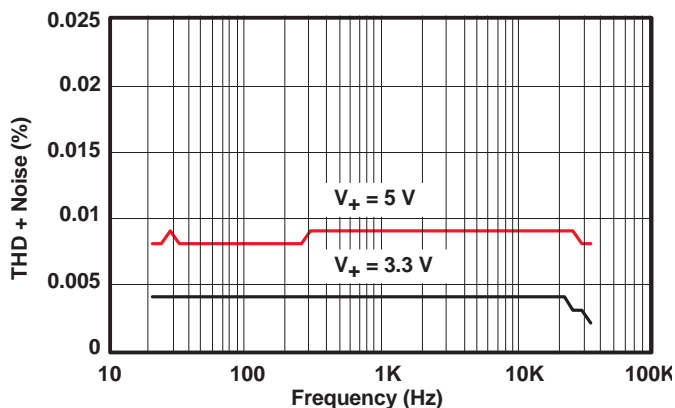


Figure 11. Total Harmonic Distortion (THD) vs. Frequency

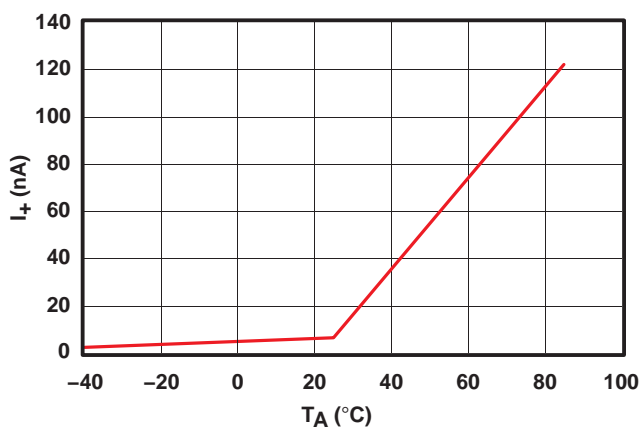


Figure 12. Power Supply Current vs Temperature ( $V_+ = 5$  V)

**TS5A3154**  
**0.9-Ω SPDT ANALOG SWITCH**  
**5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER**

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**PIN DESCRIPTION**

PIN NUMBER	NAME	DESCRIPTION
1	COM	Common
2	$\overline{\text{EN}}$	Enable control input
3	GND	Digital ground
4	GND	Digital ground
5	IN	Digital control to connect COM to NO or NC
6	NO	Normally open
7	NC	Normally closed
8	V <sub>+</sub>	Power supply

**PARAMETER DESCRIPTION**

SYMBOL	DESCRIPTION
V <sub>COM</sub>	Voltage at COM
V <sub>NC</sub>	Voltage at NC
V <sub>NO</sub>	Voltage at NO
r <sub>on</sub>	Resistance between COM and NC or COM and NO ports when the channel is ON
r <sub>peak</sub>	Peak on-state resistance over a specified voltage range
Δr <sub>on</sub>	Difference of r <sub>on</sub> between channels in a specific device
r <sub>on(flat)</sub>	Difference between the maximum and minimum value of r <sub>on</sub> in a channel over the specified range of conditions
I <sub>NC(OFF)</sub>	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state under worst-case input and output conditions
I <sub>NC(PWROFF)</sub>	Leakage current measured at the NC port during the power-off condition, V <sub>+</sub> = 0
I <sub>NO(OFF)</sub>	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state under worst-case input and output conditions
I <sub>NO(PWROFF)</sub>	Leakage current measured at the NO port during the power-off condition, V <sub>+</sub> = 0
I <sub>NC(ON)</sub>	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) open
I <sub>NO(ON)</sub>	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
I <sub>COM(ON)</sub>	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the ON state and the output (NC or NO) open
I <sub>COM(OFF)</sub>	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the OFF state and the output (NC or NO) open
I <sub>COM(PWROFF)</sub>	Leakage current measured at the COM port during the power-off condition, V <sub>+</sub> = 0
V <sub>IH</sub>	Minimum input voltage for logic high for the control input (IN, $\overline{\text{EN}}$ )
V <sub>IL</sub>	Maximum input voltage for logic low for the control input (IN, $\overline{\text{EN}}$ )
V <sub>I</sub>	Voltage at the control input (IN, $\overline{\text{EN}}$ )
I <sub>IH</sub> , I <sub>IL</sub>	Leakage current measured at the control input (IN, $\overline{\text{EN}}$ )
t <sub>ON</sub>	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, NC, or NO) signal when the switch is turning ON.
t <sub>OFF</sub>	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, NC, or NO) signal when the switch is turning OFF.
t <sub>MBB</sub>	Make-before-break time. This parameter is measured under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO) when the control signal changes state.
Q <sub>C</sub>	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NC, NO, or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, Q <sub>C</sub> = C <sub>L</sub> × ΔV <sub>COM</sub> , C <sub>L</sub> is the load capacitance, and ΔV <sub>COM</sub> is the change in analog output voltage.

**PARAMETER DESCRIPTION (continued)**

SYMBOL	DESCRIPTION
CNC(OFF)	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF
CNO(OFF)	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
CNC(ON)	Capacitance at the NC port when the corresponding channel (NC to COM) is ON
CNO(ON)	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
CCOM(ON)	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is ON
CCOM(OFF)	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is OFF
C <sub>I</sub>	Capacitance of control input (IN, $\overline{\text{EN}}$ )
O <sub>ISO</sub>	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM or NO to COM) in the OFF state.
X <sub>TALK</sub>	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This is measured in a specific frequency and in dB.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is –3 dB below the DC gain.
THD	Total harmonic distortion describes the signal distortion caused by the analog switch. This is defined as the ratio of root mean square (RMS) value of the second, third, and higher harmonic to the absolute magnitude of the fundamental harmonic.
I <sub>+</sub>	Static power-supply current with the control (IN, $\overline{\text{EN}}$ ) pin at V <sub>+</sub> or GND

## PARAMETER MEASUREMENT INFORMATION

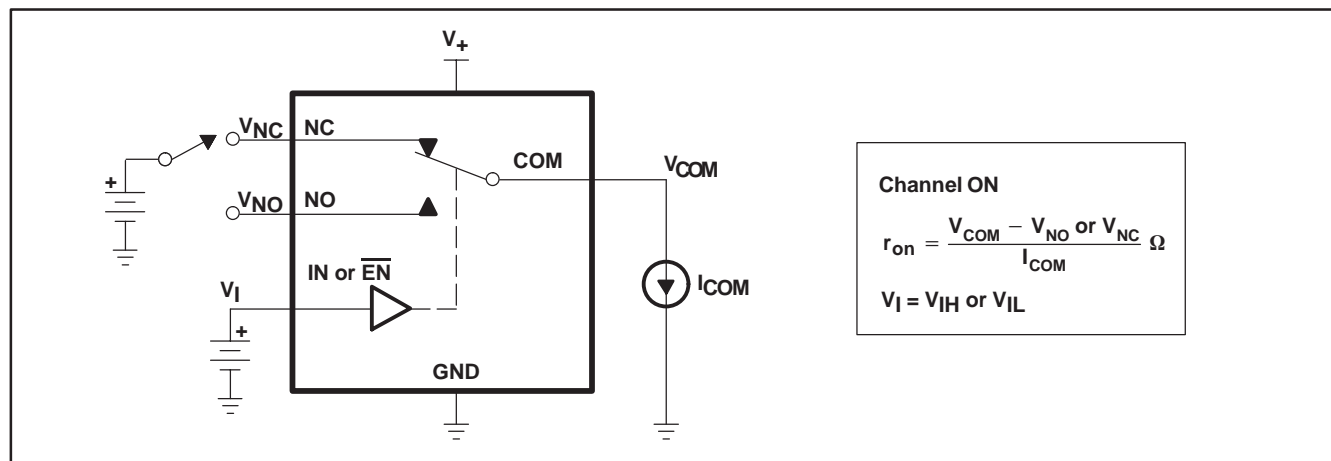


Figure 13. ON-State Resistance ( $r_{on}$ )

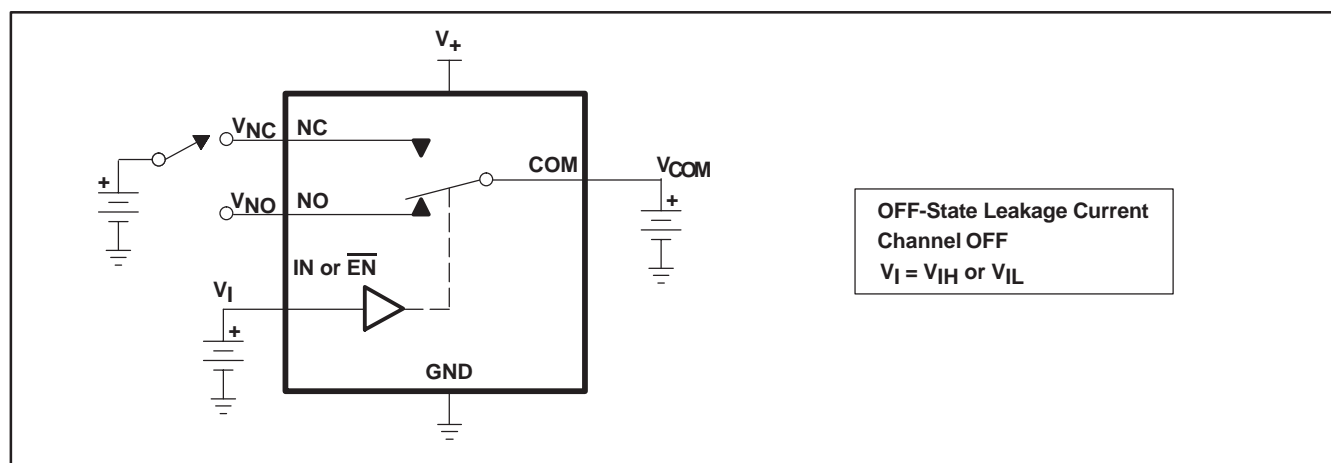


Figure 14. OFF-State Leakage Current ( $I_{NC(OFF)}$ ,  $I_{NO(OFF)}$ ,  $I_{COM(OFF)}$ ,  $I_{NO(PWROFF)}$ ,  $I_{COM(PWROFF)}$ )

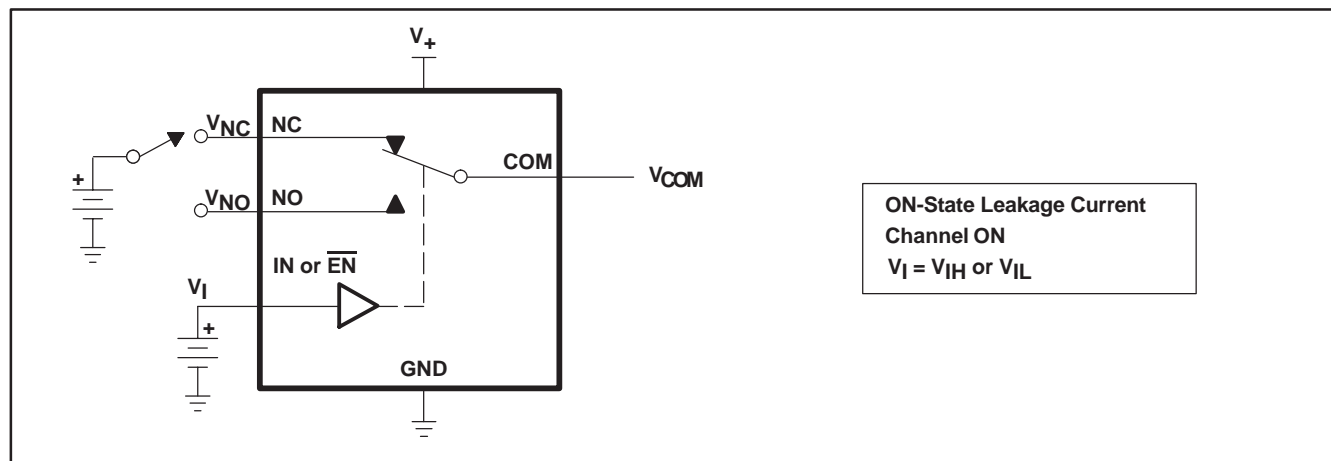


Figure 15. ON-State Leakage Current ( $I_{COM(ON)}$ ,  $I_{NC(ON)}$ ,  $I_{NO(ON)}$ )



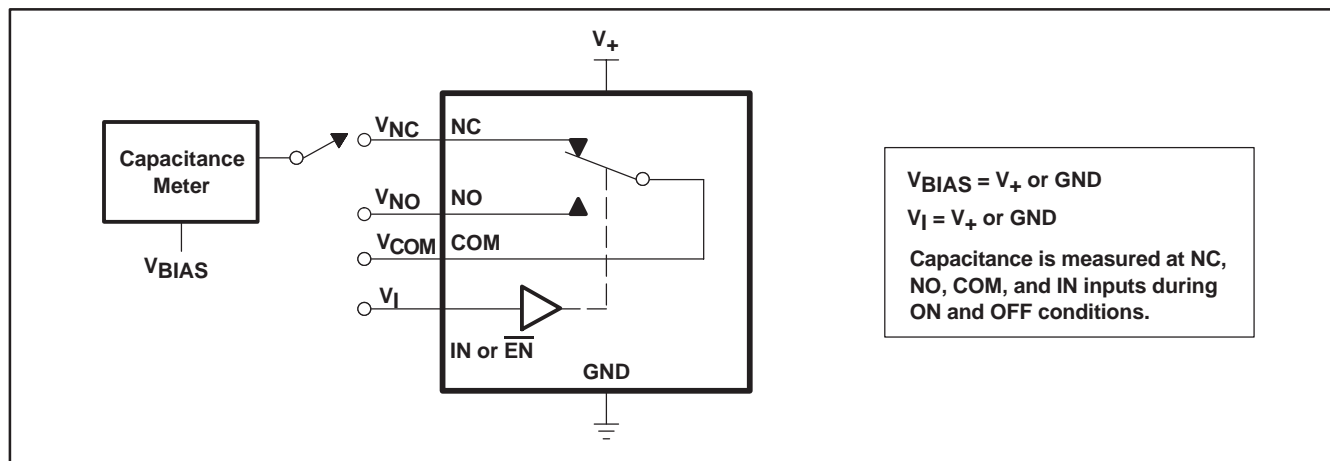
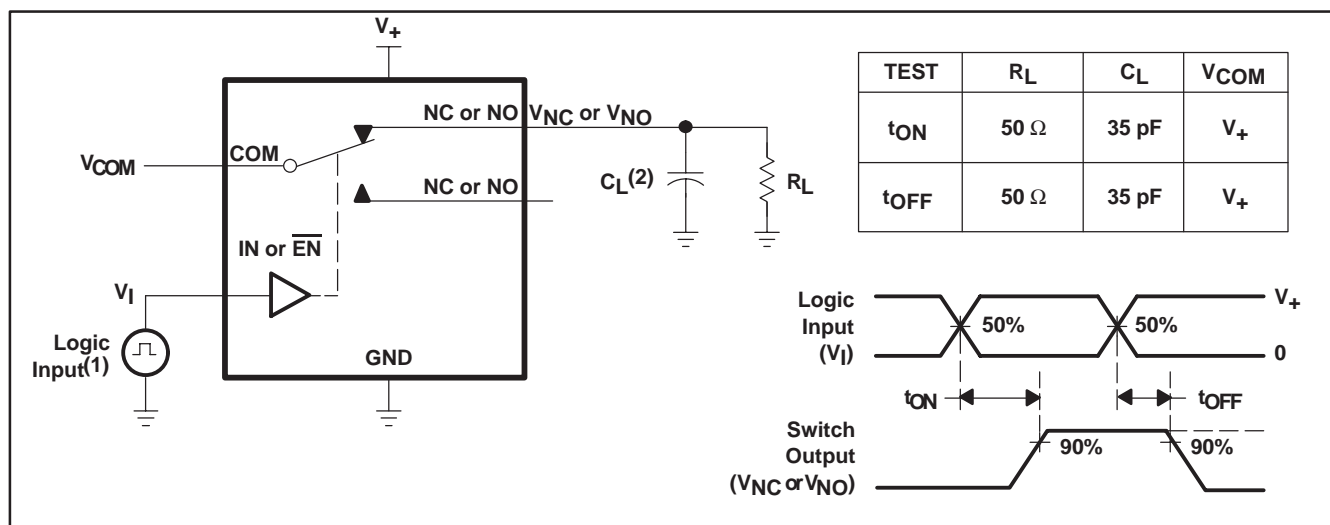


Figure 16. Capacitance ( $C_I$ ,  $C_{COM(OFF)}$ ,  $C_{COM(ON)}$ ,  $C_{NC(OFF)}$ ,  $C_{NO(OFF)}$ ,  $C_{NC(ON)}$ ,  $C_{NO(ON)}$ )



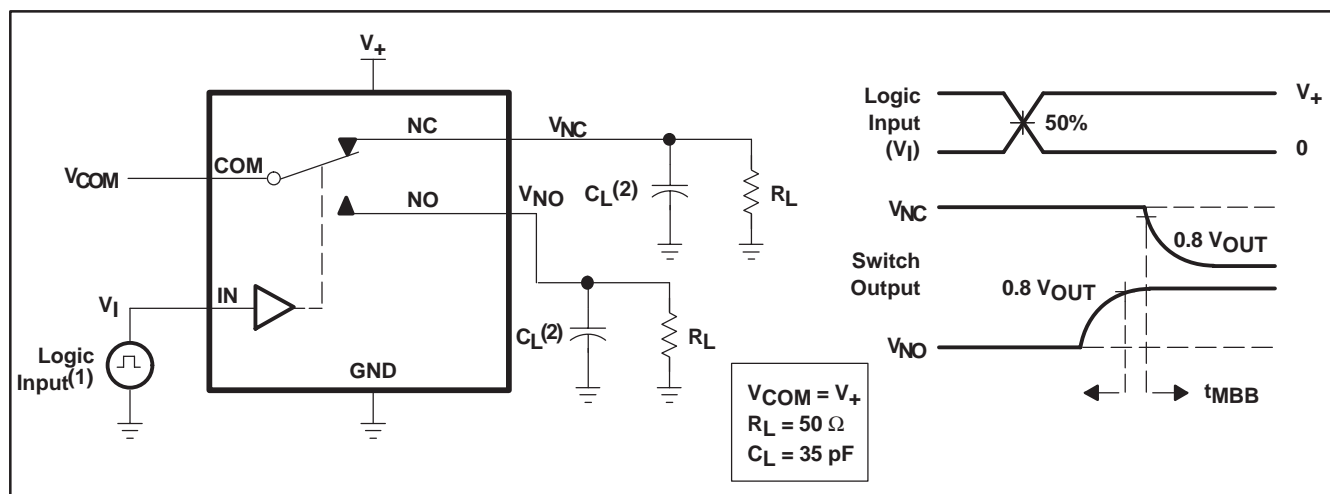
(1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> < 5 ns, t<sub>f</sub> < 5 ns.

(2) C<sub>L</sub> includes probe and jig capacitance.

Figure 17. Turn-On (t<sub>ON</sub>) and Turn-Off Time (t<sub>OFF</sub>)

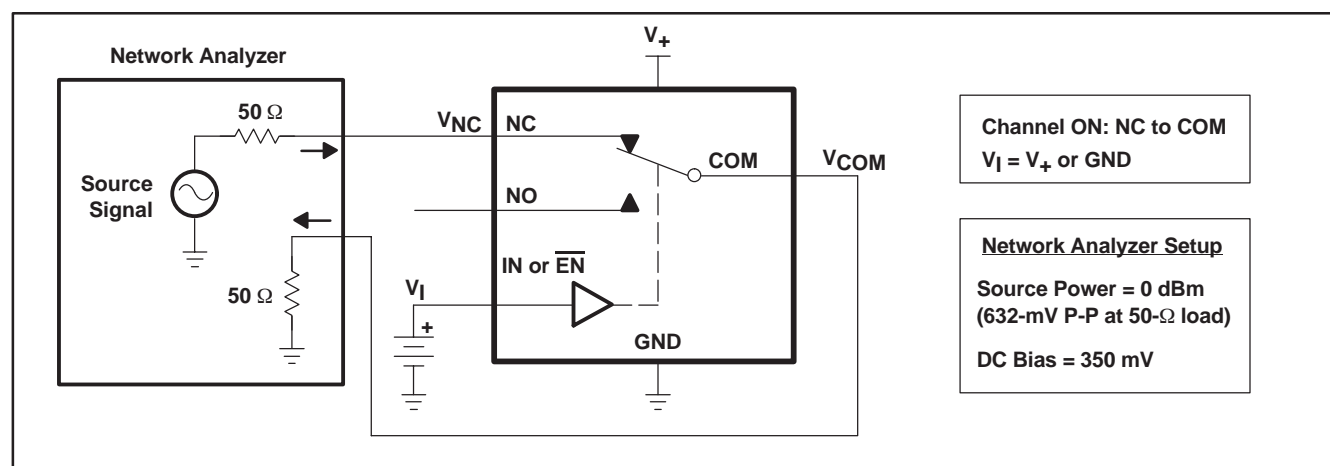
**TS5A3154**  
**0.9- $\Omega$  SPDT ANALOG SWITCH**  
**5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER**

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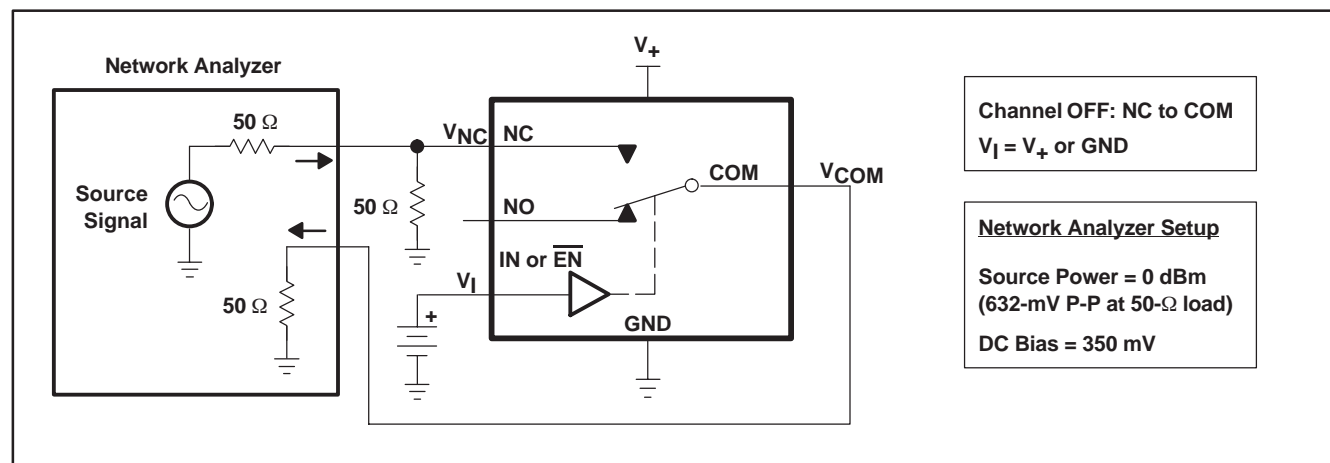


- (1) All input pulses are supplied by generators having the following characteristics:  $\text{PRR} \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .  
(2)  $C_L$  includes probe and jig capacitance.

**Figure 18. Make-Before-Break Time ( $t_{\text{MBB}}$ )**



**Figure 19. Bandwidth (BW)**



**Figure 20. OFF Isolation ( $O_{\text{ISO}}$ )**

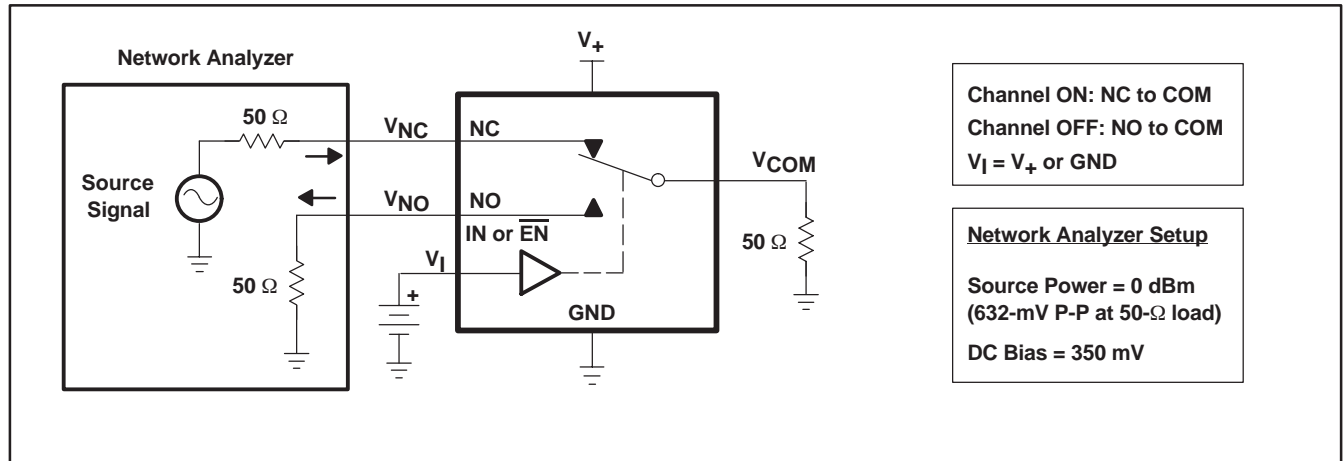
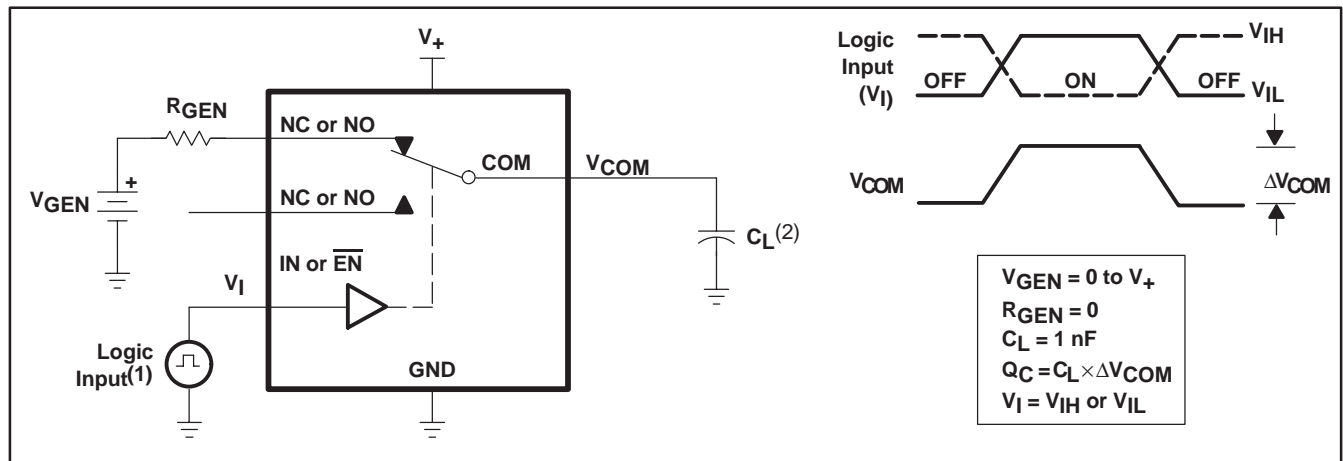
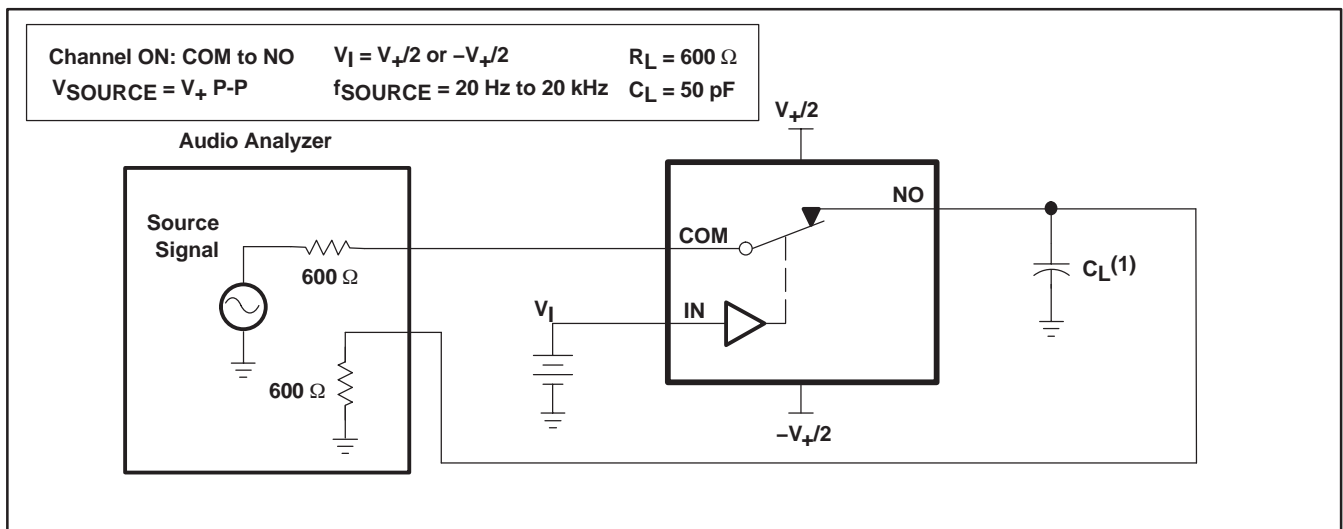


Figure 21. Crosstalk (X<sub>TALK</sub>)



- (1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub> < 5 ns, t<sub>f</sub> < 5 ns.  
(2) C<sub>L</sub> includes probe and jig capacitance.

Figure 22. Charge Injection (Q<sub>C</sub>)



- (1) C<sub>L</sub> includes probe and jig capacitance.

Figure 23. Total Harmonic Distortion (THD)

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TS5A3154DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3154DCURE4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3154DCURE6	PREVIEW	US8	DCU	8	3000	TBD	Call TI	Call TI
TS5A3154DCURG4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3154YZPR	ACTIVE	WCSP	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

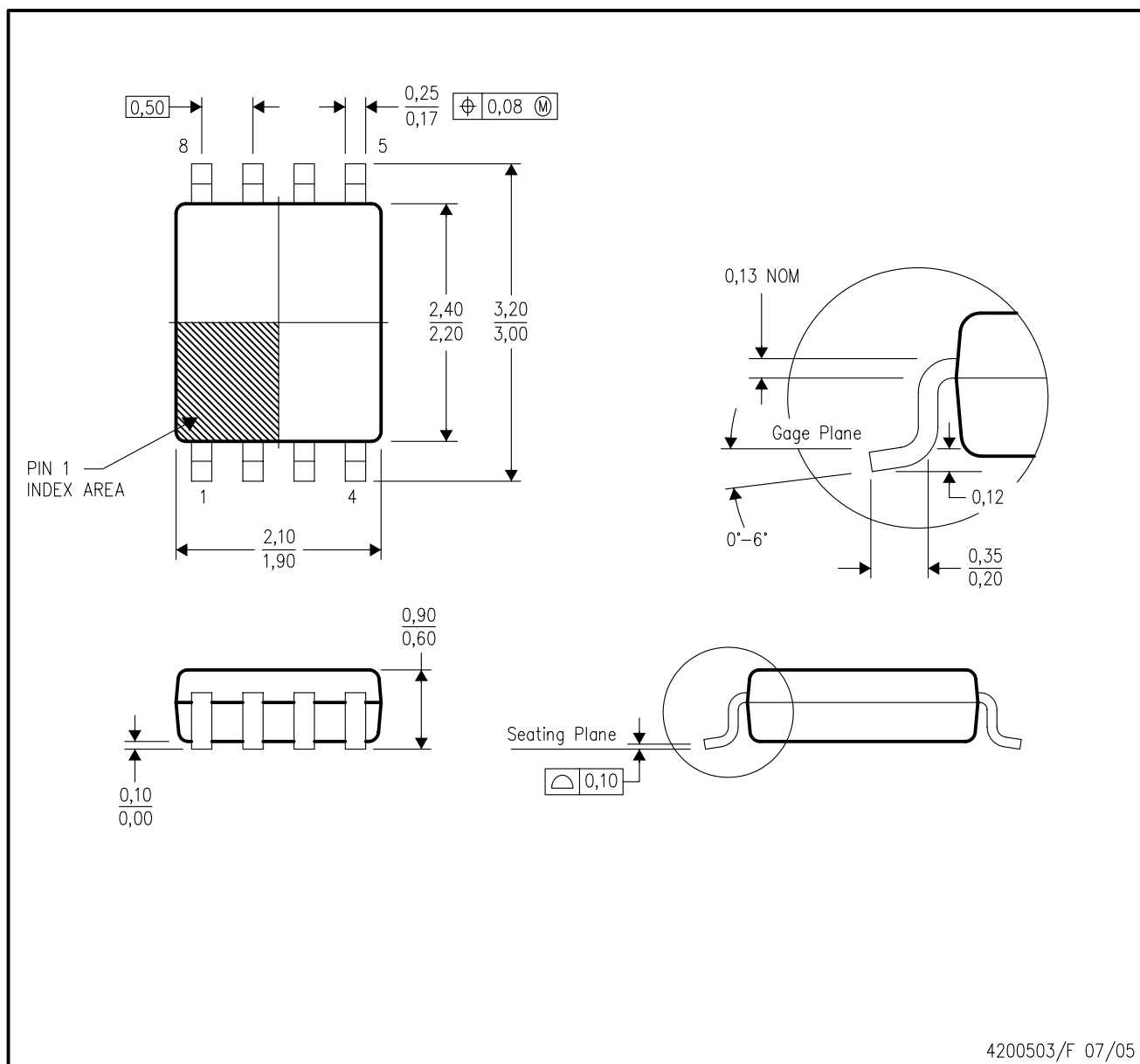
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DCU (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)

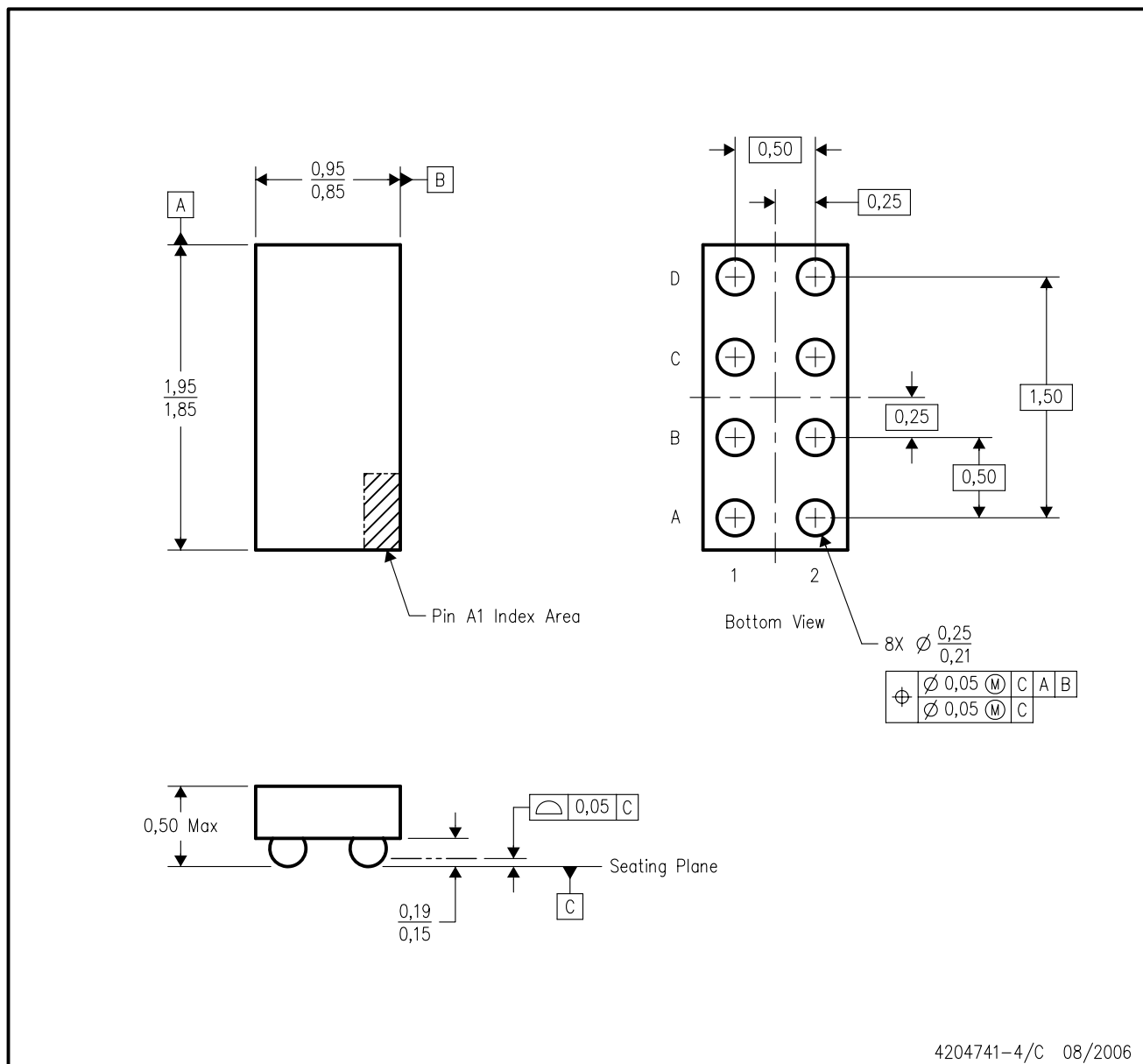


## NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Falls within JEDEC MO-187 variation CA.

## YZP (R-XBGA-N8)

## DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. This package is lead-free. Refer to the 8 YEP package (drawing 4204725) for tin-lead (SnPb).

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